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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	CAII	EXAMINER
10032941	10/31/2001	438	739	3842	<i>Edelotec</i>

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S. Clark

**CONTINUING DATA VERIFIED:

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** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed: <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO
35 USC 119 conditions met: <input type="checkbox"/> yes <input type="checkbox"/> no		13292-007001 / 2001P15322
Verified and Acknowledged Examiners's initials		
TITLE : Compliant relief wafer level packaging		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	Total Claims
			Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
		Primary Examiner	Application Examiner
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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